



**ENVIRONMENTAL AND PACKAGE TESTING DATA FOR LCC 20-28 LEAD**

<b>Stress</b>	<b>Sample Size</b>	<b>Device Hr./Cyc</b>	<b>Condition</b>	<b>Total Fails</b>	<b>Fail Percentage</b>
85/85	3,086	2,570,580	85°C, 85%RH	0	0.00
BOND INT	1,130	763,750	200°C + N2	0	0.00
HAST	6,351	658,040	130°C, 85%RH	0	0.00
HIGH TEMP STORAGE	125	124,500	200°C	0	0.00
Pressure Pot	17,744	1,471,166	121°, 15 PSIG	0	0.00
Salt Atmosphere	800	21,720	883 M1009	0	0.00
Solder DUNK	20	60	260°C, 10SEC	0	0.00
Solderability	2,016	16,888	883 M2003	0	0.00
Temp Cycle	4,822	4,058,950	-65°C - 150°C	0	0.00
Thermal Shock	9,731	1,141,740	-60°C - 150°C	0	0.00